

Material Content Data Sheet

RoHS

Sales Product Name	BTS141TC	**Issued**	16. January 2020
MA#	MA000701084		
Package	PG-TO263-3-2	**Weight***	1540.13 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	7.797	0.51	0.51	5062	5062
chip_2	inorganic material	silicon	7440-21-3	0.454	0.03	0.03	295	295
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		198	
	non noble metal	copper	7440-50-8	304.026	19.74	19.77	197402	197659
wire	non noble metal	aluminium	7429-90-5	1.750	0.11	0.11	1136	1136
encapsulation	organic material	carbon black	1333-86-4	7.319	0.48		4752	
	inorganic material	antimonytrioxide	1309-64-4	15.304	0.99		9937	
	plastics	brominated resin	-	17.300	1.12		11233	
	plastics	epoxy resin	-	126.427	8.21		82088	
	inorganic material	silicondioxide	60676-86-0	499.053	32.40	43.20	324032	432042
leadfinish	non noble metal	tin	7440-31-5	9.657	0.63	0.63	6270	6270
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	148	149
solder	non noble metal	tin	7440-31-5	0.029	0.00		19	
	noble metal	silver	7440-22-4	0.036	0.00		24	
	non noble metal	lead	7439-92-1	1.392	0.09	0.09	904	947
glue	plastics	Polyimide	26023-21-2	0.586	0.04	0.04	381	381
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		107	
	non noble metal	iron	7439-89-6	0.548	0.04		356	
	non noble metal	copper	7440-50-8	547.666	35.56	35.61	355596	356059
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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